



Position Profile: Mechanical Engineer – Electronics Packaging Design
Competition Number: US200925
Business Unit: Agriculture R & D
Reports To: Sr. Engineer/Hardware Team Leader
Location: Scottsdale, Arizona
Date: January 8, 2010

Purpose:

This position requires a senior technical specialist that can provide leadership in the development of new electronic packaging capabilities for the company. Using a solid background in the development of a variety of packaging solutions, this position will implement a competitive and forward looking packaging strategy across all product lines and will develop the internal competencies to ensure successful implementation of same.

Responsibilities:

- Plan, develop and implement innovative design solutions for the packaging of complex GNSS based machine guidance and positioning electronics systems
- Develop complex parametrically driven 3D CAD models and assemblies
- Participate in design reviews, preparing and presenting mechanical engineering input
- Interface with marketing, vendors and manufacturing operations to resolve requirements for new product development, design issues, product use concerns, production issues, and field problems
- Mock-up, prototype and assemble concept packaging
- Produce complete, optimized designs taking into account functional, cost, sourcing, production, and time to market considerations
- Create test plans and procedures for product qualification, acceptance testing of electronic packaging, and validation of designs of new components to be used in new product designs
- Work within an integrated product team
- Support production and manufacturing activities such as planning, assembly, materials procurement, and test
- Follow relevant ISO and CMMI processes and provide feedback and support for process improvement.
- Mentor intermediate and junior mechanical design staff
- Other related duties as assigned by Management and/or Leadership Team.

Education and Experience:

- MScME Degree or equivalent in Mechanical Engineering or Industrial Design from a recognized institute
- 10+ years experience in directly related activities related to electronics packaging in related environments
- Proficiency in Solid Works and Pro/Engineer required, experience with COSMOS, AutoCAD, Flowtherm desirable
- Demonstrated experience related to Knowledge/Skills and Responsibilities identified above

Demonstrated Competence in the following:

- Proficient in 3D solid modeling using SolidWorks
- Use of advanced CAD tools
- Mechanical and thermal finite element modeling and simulation desired, not necessary
- Packaging gasket and joint design for harsh environments
- EMI considerations for packaging design
- Ergonomic design considerations including use and safety considerations
- ASME Y14.5 Geometric Dimensions and Tolerancing techniques

- Packaging standards associated with such standards as IPXX, EP455, ISO and ANSI
- Sheet, casting, extrusion and machining production techniques in plastic and metals
- Production techniques associated with original manufacture and repair of electronic packaging assemblies

Apply

- Send Resume to careers@hemispheregps.com
- **Please quote competition number US200925**
- No phone calls please

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